2SC4808

Silicon NPN epitaxial planar type

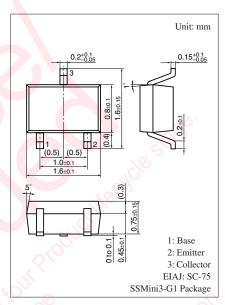
For UHF band low-noise amplification

Features

- Low noise figure NF
- High forward transfer gain $|S_{21e}|^2$
- High transition frequency f_T
- SS-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

Absolute Maximum Ratings $T_a = 25^{\circ}C$

| Parameter | Symbol | Rating | Unit |
|---------------------------------------|------------------|-------------|------|
| Collector-base voltage (Emitter open) | V _{CBO} | 15 | V |
| Collector-emitter voltage (Base open) | V _{CEO} | 10 | v |
| Emitter-base voltage (Collector open) | V _{EBO} | 2 | V |
| Collector current | I _C | 80 | mA |
| Collector power dissipation | P _C | 125 | mW |
| Junction temperature | Tj | 125 | °C |
| Storage temperature | T _{stg} | -55 to +125 | °C |
| | | | |



Marking Symbol: 3M

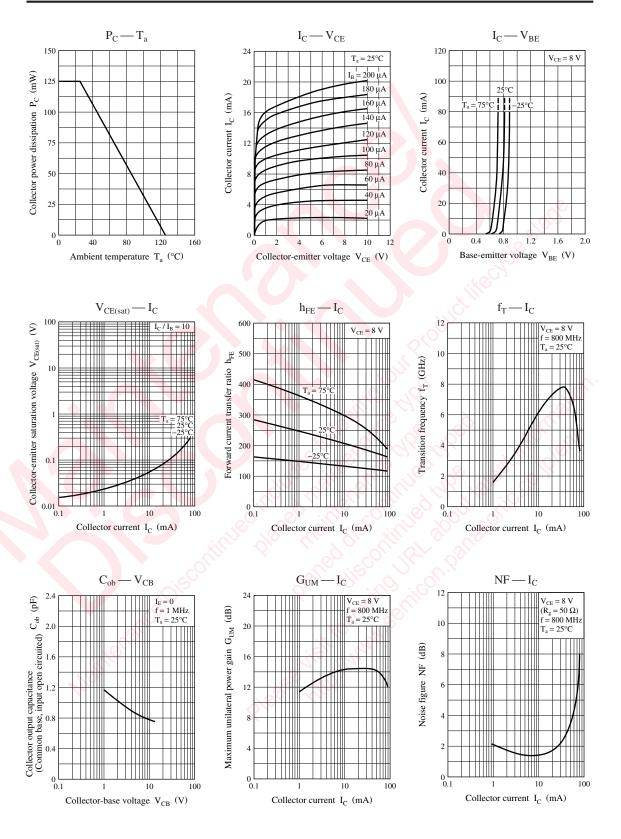
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|---|---------------------------------|---|------------|-----|-----|------|
| Collector-base voltage (Emitter open) | V _{CBO} | $I_{\rm C} = 10 \ \mu A, I_{\rm E} = 0$ | 15 | 3 | | V |
| Collector-emitter voltage (Base open) | V _{CEO} | $I_{\rm C} = 100 \ \mu \text{A}, I_{\rm B} = 0$ | 10 | | | V |
| Collector-base cutoff current (Emitter open) | I _{CBO} | $V_{CB} = 10 \text{ V}, I_E = 0$ | $\sqrt{2}$ | | 1 | μΑ |
| Emitter-base cutoff current (Collector open) | I _{EBO} | $V_{EB} = 2 V, I_C = 0$ | | | 1 | μΑ |
| Forward current transfer ratio * | h _{FE} | $V_{CE} = 8 V, I_C = 20 mA$ | 50 | 150 | 300 | |
| Transition frequency | f _T | $V_{CE} = 8 \text{ V}, I_{C} = 15 \text{ mA}, f = 0.8 \text{ GHz}$ | 5 | 6 | | GHz |
| Collector output capacitance (Common base, input open circuited) | C _{ob} | $V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$ | | 0.7 | 1.2 | pF |
| Forward transfer gain | S _{21e} ² | $V_{CE} = 8 \text{ V}, I_{C} = 15 \text{ mA}, f = 0.8 \text{ GHz}$ | 11 | 14 | | dB |
| Maximum unilateral power gain | G _{UM} | $V_{CE} = 8 \text{ V}, I_{C} = 15 \text{ mA}, f = 0.8 \text{ GHz}$ | | 15 | | dB |
| Noise figure | NF < | $V_{CE} = 8 \text{ V}, \text{ I}_{C} = 7 \text{ mA}, \text{ f} = 0.8 \text{ GHz}$ | | 1.3 | 2.0 | dB |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Pulse measurement

Panasonic



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